



IEC 62899-202-8

Edition 1.0 2024-03

INTERNATIONAL STANDARD



**Printed electronics –
Part 202-8: Materials – Conductive ink – Measurement of difference in
resistance of printing direction of conductive film fabricated with wire-shaped
materials**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.180; 87.080

ISBN 978-2-8322-8432-2

Warning! Make sure that you obtained this publication from an authorized distributor.

CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references	6
3 Terms and definitions	6
4 Test sample, apparatus and measuring device	7
4.1 Measurement environmental conditions	7
4.2 Test apparatus.....	7
4.3 Measuring device.....	8
4.4 Sample preparation for measuring resistance difference with printing direction.....	8
5 Test procedure	9
6 Report	9
6.1 Reporting the resistance	9
6.2 Report of the results	10
Annex A (informative) Measurement of difference of printing direction of printed conductive film.....	11
A.1 Sample preparation.....	11
A.2 Settings for the test sample	11
Bibliography.....	13
Figure 1 – Schematic diagram of printed conductive film with screws for a four-wire measurement.....	8
Figure 2 – Samples with printing direction of conductive film fabricated with wire- shaped materials	9
Figure A.1 – Sample preparation.....	11
Figure A.2 – Holder with setting a test sample	12
Table 1 – Resistance range of the test piece and the applied current.....	8
Table A.1 – Test results	12

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED ELECTRONICS –

**Part 202-8: Materials – Conductive ink – Measurement of difference
in resistance of printing direction of conductive film
fabricated with wire-shaped materials**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) IEC draws attention to the possibility that the implementation of this document may involve the use of (a) patent(s). IEC takes no position concerning the evidence, validity or applicability of any claimed patent rights in respect thereof. As of the date of publication of this document, IEC had not received notice of (a) patent(s), which may be required to implement this document. However, implementers are cautioned that this may not represent the latest information, which may be obtained from the patent database available at <https://patents.iec.ch>. IEC shall not be held responsible for identifying any or all such patent rights.

IEC 62899 has been prepared by IEC technical committee 119: Printed electronics. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
119/476/FDIS	119/483/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

IMPORTANT – The "colour inside" logo on the cover page of this document indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

The printing process for fabricating flexible devices is a very promising technology due to its high conductivity and efficiency. Specifically, a printed metal-based conductive layer on a flexible substrate can be employed as electrode or be interconnected for flexible devices. It can be commercialized as a type of composite material where the conductive layer is formed on the substrate as a conductor.

For metal-based transparent conductive (TC) films, silver or copper nanowires or metal mesh on a flexible substrate are a key component for many recently developed electronic products, ranging from smartphones to keypads of appliances such as refrigerators and washing machines. While indium tin oxide (ITO) is the conventional material for TC films, metal-based TC films fabricated using printed electronics technologies are being increasingly used as an alternative. TC film-fabricated nanowires have superior intrinsic properties owing to their wire shape. Their electrical performance can differ based on the printing direction and ink properties. The alignment of a wire depends on the printing equipment, ink composition, printing process, etc. [1] to [3]¹.

In this document, a method to evaluate the difference in electrical properties based on the printing direction is proposed. In particular, the proposed method monitors changes in the resistance of a printed metal-based TC film on a flexible substrate.

¹ Numbers in square brackets refer to the Bibliography.

PRINTED ELECTRONICS –

Part 202-8: Materials – Conductive ink – Measurement of difference in resistance of printing direction of conductive film fabricated with wire-shaped materials

1 Scope

This part of IEC 62899 provides a method for measuring the resistance difference of the printing direction of a printed conductive layer with wire-shaped or wire-type conducting materials. The method described in this document offers a measurement method and conditions for solution processed conductive films, fabricated by coating and printing process.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62899-201, *Printed electronics – Part 201: Materials – Substrates*

IEC 62899-202, *Printed electronics – Part 202: Materials – Conductive ink*

ISO 291, *Plastics – Standard atmospheres for conditioning and testing*